

## **General Description**

The WSF50N10 is the highest performance trench N-Ch MOSFET with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WSF50N10 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

#### **Features**

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent Cdv/dt effect decline
- Green Device Available

## **Product Summery**

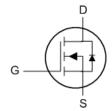
BV <sub>DSS</sub>	R <sub>DSON</sub>	I <sub>D</sub>
100V	22mΩ	50A

# **Applications**

- High Frequency Point-of-Load Synchronous Buck Converter
- Networking DC-DC Power System
- Load Switch

# **TO-252 Pin Configuration**





# **Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	100	V
$V_{GS}$	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	50	Α
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	25	Α
I <sub>D</sub> @T <sub>A</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	6.7	А
I <sub>D</sub> @T <sub>A</sub> =70℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	5.3	А
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	160	Α
EAS	Single Pulse Avalanche Energy <sup>3</sup>	81	mJ
I <sub>AS</sub>	Avalanche Current	18	А
P <sub>D</sub> @T <sub>C</sub> =25℃	Total Power Dissipation <sup>4</sup>	83	W
P <sub>D</sub> @T <sub>A</sub> =25℃	Total Power Dissipation <sup>4</sup>	33	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	℃
T <sub>J</sub>	Operating Junction Temperature Range -55 to 150		℃

## **Thermal Data**

Symbol	Parameter	Тур.	Max.	Unit
$R_{ heta JA}$	Thermal Resistance Junction-ambient <sup>1</sup>		50	°C/W
$R_{ heta JC}$	Thermal Resistance Junction-Case <sup>1</sup>		1.5	°C/W

**N-Ch MOSFET** 

# Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS}$ =0 $V$ , $I_D$ =250 $u$ A	100			V
$\triangle BV_{DSS}/\triangle T_{J}$	BVDSS Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =1mA		0.098		V/°C
D	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V , I <sub>D</sub> =20A		22	28	
R <sub>DS(ON)</sub>		V <sub>GS</sub> =4.5V , I <sub>D</sub> =15A		24	32	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	\/ -\/   -250\	1.0	2.0	3.0	V
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	$V_{GS}=V_{DS}$ , $I_D=250uA$		-5.52		mV/℃
	Drain Source Leakage Current	V <sub>DS</sub> =80V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C			10	uA
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =80V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C			100	
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}$ = $\pm 20 V$ , $V_{DS}$ = $0 V$			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =20A		25.7		S
Rg	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		1.0	1.2	Ω
$Q_{g}$	Total Gate Charge (10V)			50	65	
Q <sub>gs</sub>	Gate-Source Charge	V <sub>DS</sub> =30V , V <sub>GS</sub> =10V , I <sub>D</sub> =20A		8	14	nC
Q <sub>gd</sub>	Gate-Drain Charge			10	18	
T <sub>d(on)</sub>	Turn-On Delay Time			18	33	
Tr	Rise Time	V <sub>DD</sub> =30V , V <sub>GS</sub> =10V,I <sub>D</sub> =20A		9	17	
T <sub>d(off)</sub>	Turn-Off Delay Time			56	101	ns
T <sub>f</sub>	Fall Time			14	26	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =30V , V <sub>GS</sub> =0V , f=1MHz		2450	3180	
C <sub>oss</sub>	Output Capacitance			150	192	pF
C <sub>rss</sub>	Reverse Transfer Capacitance			85	115	]

#### **Guaranteed Avalanche Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	Single Pulse Avalanche Energy <sup>5</sup>	V <sub>DD</sub> =25V , L=0.1mH , I <sub>AS</sub> =18A	80			mJ

#### **Diode Characteristics**

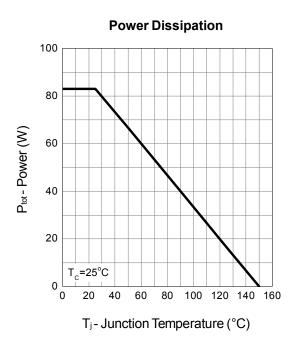
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I <sub>S</sub>	Continuous Source Current <sup>1,6</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			20	Α
I <sub>SM</sub>	Pulsed Source Current <sup>2,6</sup>				45	Α
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =20A , T <sub>J</sub> =25℃			1.3	V
t <sub>rr</sub>	Reverse Recovery Time	   IF=20A , dl/dt=100A/µs , T <sub>J</sub> =25℃		40		nS
Q <sub>rr</sub>	Reverse Recovery Charge			83		nC

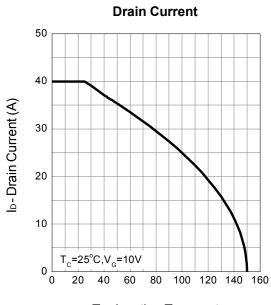
#### Note:

- 1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper,t<10sec.
- 2.The data tested by pulsed , pulse width  $\,\leq\,300\text{us}$  , duty cycle  $\,\leq\,2\%$
- 3. The EAS data shows Max. rating . The test condition is  $V_{DD}$ =25V,  $V_{GS}$ =10V, L=0.1mH,  $I_{AS}$ =18A
- 4.The power dissipation is limited by 150  $^{\circ}\mathrm{C}$  junction temperature
- 5. The Min. value is 100% EAS tested guarantee.
- 6. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.



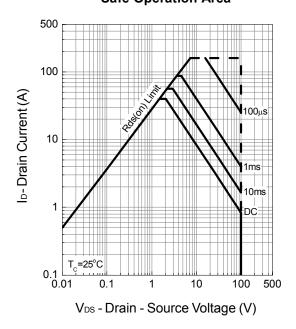
# **Typical Characteristics**



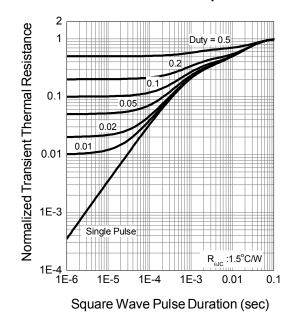


T<sub>j</sub> - Junction Temperature

# Safe Operation Area



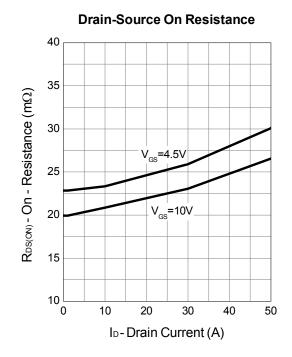
#### **Thermal Transient Impedance**

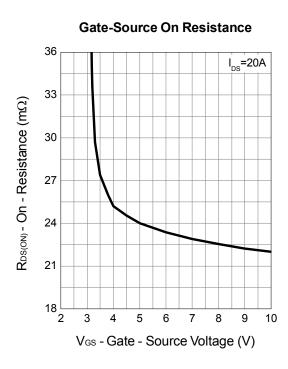


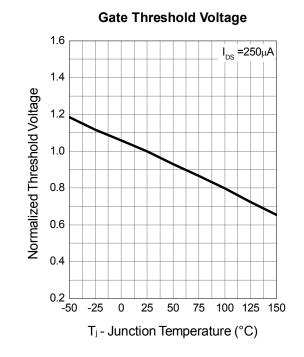


# **Typical Characteristics**

# Output Characteristics 60 50 V<sub>SS</sub>=3.5,4,5,6,7,8,9,10V 30 10 10 10 2.5V V<sub>DS</sub>- Drain - Source Voltage (V)

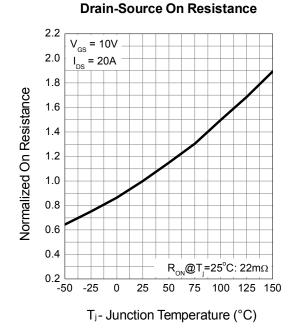




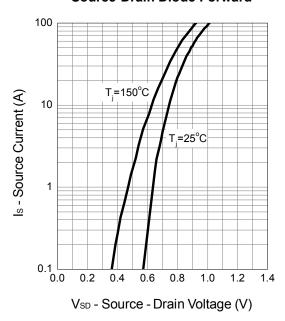




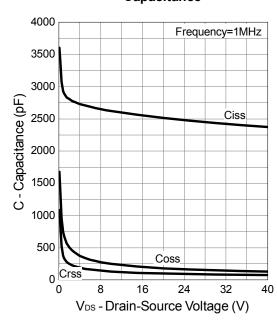
# **Typical Characteristics**



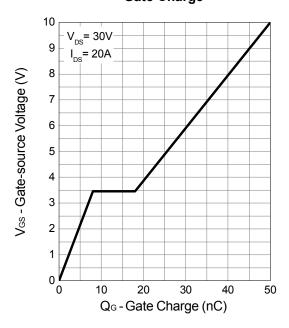
#### **Source-Drain Diode Forward**







# **Gate Charge**





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